

## Application Data Sheet

### Application Information

Application Type:: Regular  
Subject Matter:: Utility  
Title:: A Method For Reducing Stress  
Concentrations On A Semiconductor  
Wafer By Surface Laser Treatment  
Attorney Docket Number:: TI-34900 (1962-05300)  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 1  
Total Drawing Sheets:: 7  
Small Entity?:: No

### Applicant Information

Applicant Authority type:: Inventor  
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Status:: Full Capacity  
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Applicant Authority type:: Inventor  
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**Representative Information**

Representative Customer Number:: 23494

**Assignee Information**

Assignee name:: Texas Instruments Incorporated  
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